

10/538905

JC17 Rec'd PCT/PTO 14 JUN 2005

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Nicole Barrese 6/14/05
(Signature & date)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
H. Bernhard Pogge et al.

Examiner: not yet assigned

Application No.: not yet assigned

Group Art Unit: not yet assigned

Filed: herewith

For: THREE-DIMENSIONAL DEVICE
FABRICATION METHOD

Date 6/14/2005

INFORMATION DISCLOSURE STATEMENT

The Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Pursuant to the duty of disclosure set forth in 37 C.F.R. § 1.56, and in accordance with the provisions of 37 C.F.R. §§ 1.97 and 1.98, the undersigned attorney respectfully submits copies of the US patent and publications as listed on Form PTO-1449, attached hereto.

No representation is made or intended as to the pertinency of the disclosed information, that information more pertinent than that listed is not available, or that other information is not applicable.

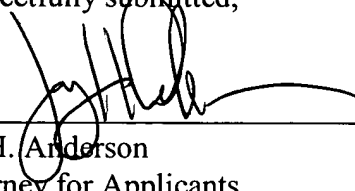
No fee is believed to be due for this submission. If any fees are required, however, the Commissioner is hereby authorized to charge such fees to Deposit Account No. 09-0458.

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The applicant's undersigned attorney may be reached by telephone at (845) 894-3667.
All correspondence regarding this Information Disclosure Statement should be directed to the
below listed address.

Respectfully submitted,



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INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional) FIS920020139US1		Application Number 107538705
Applicant(s) H. Bernhard Pogge et al.		
Filing Date herewith	Group Art Unit not yet assigned	

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
		4,889,832	12/26/1989	Chatterjee			
		5,268,326	12/7/1993	Lesk et al.			
		6,489,217	12/3/2002	Kalnitsky et al.			
		5,091,331	2/25/1992	Delgado et al.			
		5,627,106	5/6/1997	Hsu			
		6,444,560	9/3/2002	Pogge et al.			

FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

		J.-Q. Lu et al., "Fabrication of via-chain test structures for 3D IC technology using dielectric glue bonding on 200 mm wafers," Materials Research Society ULSI XVII Conference Proceedings 151 (2002)
		P. Ramm et al., "Interchip via technology by using copper for vertical system integration," Materials Research Society Advanced Metallization Conference 159 (2002)

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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(Use several sheets if necessary)

Docket Number (Optional)
FIS920020139US1

Application Number
not yet assigned

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*EXAMINER
INITIAL

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Rahman et al., "Thermal analysis of three dimensional integrated circuits," IEEE International Interconnect Technology Conference Proceedings 157 (2001)

EXAMINER

DATE CONSIDERED

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.